

BST-21503A 150g 有铅 LED BGA SMD PGA 焊膏



100 支装

锡膏

适用于 LED BGA SMD PGA 等封装

符合 RoHS 标准

PC 板适用



BST-21503A

60℃

150g / pc

PRODUCT DISPLAY



PRODUCT DETAILS



Name: Soldering Paste

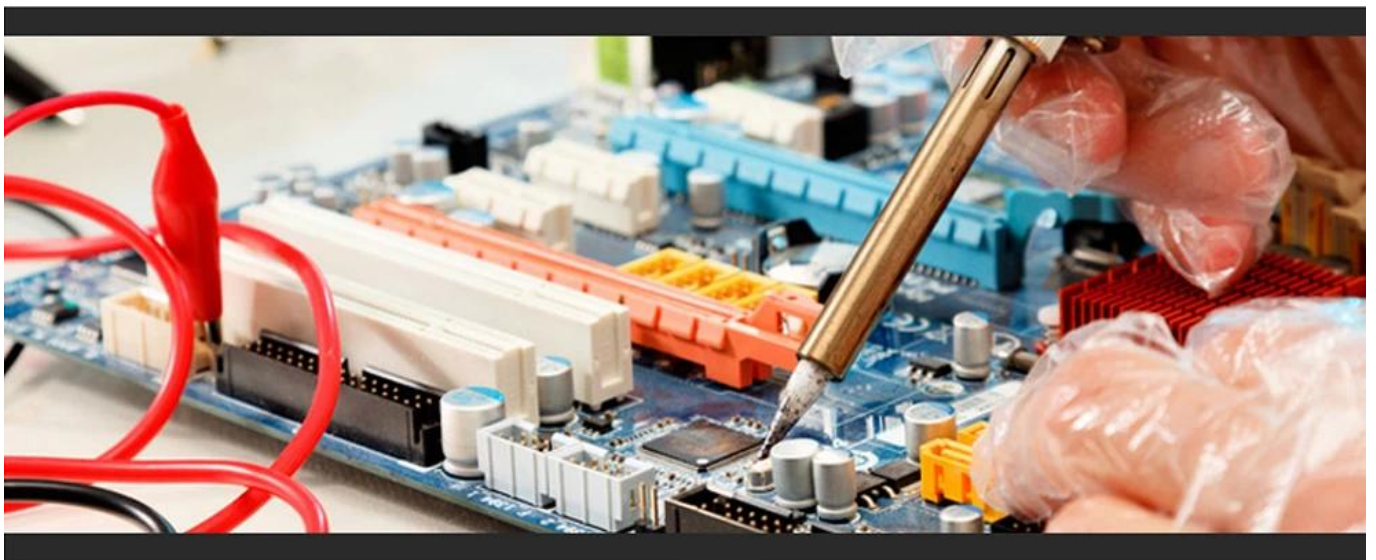
Size: $\Phi 80 \times 45\text{mm}$

Composition: Solder powder, resin

Model: BST-21503A

Weight: 100g

Melting point: 60°C





- ▲ Stable performance, Not volatile, long life cycle, the amount of province;
- ▲ Non-toxic non-irritating odor, the use of safe and reliable;
- ▲ The IC and PCB are not corrosive
- ▲ Its boiling point is only slightly higher than the melting point of solder.

Features: Solder melting at the time of soldering begins to boil endothermic vaporization, which can be maintained at this temperature using IC and PCB temperatures. In the demolition of the chip with a lot of solder paste, it melts fast, you can flow to the BGA chip below. Rosin is solid without solder paste convenient.

PRODUCT PHOTOGRAPH



